PCN Number	:	20210	210916000.1			CN D	ate:	September 20, 202	
	Qualification of additional Fab site (UMC-F12) and additional Assembly site (CARZ) for select LBC9 devices								
Customer Co	ntact:	<u>P</u> (	PCN Manager			ept:		Quality Services	
Proposed 1 <sup>st</sup> Ship Date:			Dec 20, 2021 Estin				nple	Date provided at	
			Availa			ity:	sample request.		
Change Type			7 I				1 .		
Assembly	/ Site			/ Process		Assembly Materials			
Design			_	Specificat		+		nical Specification	
Test Site		<u> </u>		Shipping/L ımp Materi		H	Test P	Bump Process	
<ul><li>Wafer Bu</li><li>✓ Wafer Fa</li></ul>			_	b Material		+		Fab Process	
<u> </u>	D Site	<u> </u>		b Material		+-	Walei	Tab Flucess	
				N Detai					
Description (	of Change		PC	in Detai	15				
exas Instrumussembly site	(CARZ) for	the sele	ected devices			ıct Afi	ected" s		
	Current F	ab Site	1			Nev	<i>i</i> Fab Si	ite	
Current Fa	b Proc	ess	Wafer		w Fab	Pi	rocess	Wafer	
Site			Diameter		Site			Diameter	
RFAB	LBO	29	300 mm	UM	C-F12		LBC9	300 mm	
					struction d				
				CI	DAT		CARZ		
	Mold C	ompoun	d				<b>CARZ</b> D#44108		
		ompoun Compou		422	DAT	SII		86	
_	Mount re provided	Compou	ınd	422 420	<b>DAT</b> 22198	SII	)#44108	86	
	Mount re provided	Compou	ınd	422 420	<b>DAT</b> 22198	SII	)#44108	86	
Reason for C	Mount re provided Change:	Compou	ınd	422 420	<b>DAT</b> 22198	SII	)#44108	86	
Reason for Continuity of season for Continuity	Mount re provided Change: supply	in the C	ind Qual Data Se	422 420 ection.	DAT 22198 07123	SII	D#44108 D#4431!	86	
Reason for Continuity of a Anticipated in None	Mount re provided change: supply impact on	in the C	ual Data Se	422 420 ection.	DAT 22198 07123	SII	D#44108 D#4431!	86 56	
Reason for Continuity of a Anticipated in None	Mount re provided change: supply impact on	in the C	ual Data Se	422 420 ection.	DAT 22198 07123	SII	D#44108 D#4431!	86 56	
Reason for Continuity of a Anticipated in None Impact on E	Mount re provided change: supply impact on	in the C	ual Data Se  it, Function ings:	422 420 ection.	DAT 22198 07123 or Relial	SII	0#44108 0#44319 (positiv	86 56	
Reason for Continuity of a Anticipated in None Impact on E	Mount re provided Change: supply impact on nvironmen	in the C	ind Data Se  it, Function ings: s of environi	422 420 ection. n, Quality	DAT 22198 07123 or Relial	SII SIII	0#44108 0#4431! (positive	ve / negative):	
Reason for Continuity of a Anticipated in None Empact on Endaged in Checked boxe	Mount re provided change: supply impact on nvironmen es indicate to ow boxes a	in the C	ind Data Se  it, Function ings: s of environi	422 420 cction.  n, Quality mental ratie no change	DAT 22198 07123 or Relial	SII SIII SIII siii sii sii sii sii sii sii sii sii	0#44108 0#4431! (positive	ve / negative):	
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Reason for Continuity of a Anticipated in None  Impact on Enterprise Checked boxes change. If belied in Ro	Mount re provided Change: supply impact on nvironment es indicate to ow boxes a HS age	Form,	ind Dual Data Se  it, Function ings: s of environmed, there ar  REACH Change	422 420 ction.  n, Quality mental rate no change	or Relial ings follow ges to the Green Sta	SII SIII sility	(positive mplementiated en	ve / negative):  ntation of this nvironmental rating IEC 62474	
Reason for Continuity of a Anticipated in None Impact on Enchecked boxed hange. If beling No Character is no Changes to proceed the Changes to proceed in the Changes to proce	Mount re provided Change: supply impact on nvironment es indicate tow boxes a HS age product ide	Form,	ind Dual Data Se  it, Function ings: s of environmed, there ar  REACH Change	422 420 ction.  n, Quality mental rate no change	or Relial ings follow ges to the Green Sta	SII SIII sility	(positive mplementiated en	ve / negative):  ntation of this nvironmental rating IEC 62474	
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None  Impact on Exchange. If belonge No Char  Changes to pure the Site Information of the Site Informa	Mount re provided Change: supply impact on nvironmen es indicate to ow boxes a HS age product ide formation:	Form,	ind Qual Data Se  it, Function ings: s of environmed, there ar  REACH Change tion resultin rigin Code L)	422 420 action.  m, Quality mental rate no change   Quality mg from t	or Relial ings follow ges to the Green Sta No Change his PCN:	SII SIII sility	(positive mplementiated en	ve / negative):  ntation of this nvironmental rating IEC 62474 No Change	

**Assembly Site** 

CDAT

**CARZ** 

**Assembly Site Information:** 

CHN

**CHN** 

Assembly Site Origin (22L) | Assembly Country Code (23L)

CDA

CSZ

**Assembly City** 

Chengdu

Jiangsu

# Sample product shipping label (not actual product label)

TEXAS INSTRUMENTS MADE IN: Malaysia 2DC: 2Q;

MSL 2 /260C/1 YEAR SEAL DT MSL 1 /235C/UNLIM 03/29/04

OPT: ITEM: (L)T0:1750 5A LBL:



(1P) SN74LS07NSR (a) 2000 (D) 0336 (31T)LOT: 3959047MLA (4W) TKY(1T) 7523483812

(2P) REV: (V) 0033317 (20L) 650: SHE (21L) CCO:USA (22L) ASO: MLA (23L) ACO: MYS

# **Product Affected:**

Group 1 - Adding UMC-F12 Fab Site, CARZ Assembly Site and BOM updates:							
SN1905015RSMR	SN1905031RSMR	SN2011036RSMR	TPS25814RSMT				
SN1905016RSMR	SN2009014RSMR	SN2011037RSMR	TPS25815RSMR				
SN1905020RSMR	SN2009015RSMR	SN2011054RSMR	TPS65991ADRSMR				
SN1905022RSMR	SN2009016RSMR	SN2011055RSMR	TPS65991AERSMR				
SN1905023RSMR	SN2009017RSMR	SN2011057RSMR	TPS65992SADRSMR				
SN1905025RSMR	SN2009018RSMR	SN2102044RSMR	TPS65992SAERSMR				
SN1905026RSMR	SN2009019RSMR	TPS25750SRSMR					
SN1905028RSMR	SN2010019RSMR	TPS25814RSMR					

Group 2 - Adding UMC-F12 Fab Site only:						
SN1905024RJKR	SN2009016RJKR	SN2010020RJKR	SN2011053RJKR			
SN1905027RJKR	SN2009017RJKR	SN2011031RJKR	TPS25750DRJKR			
SN2009014RJKR	SN2009018RJKR	SN2011032RJKR	TPS65992DADRJKR			
SN2009015RJKR	SN2009019RJKR	SN2011033RJKR	TPS65992DAERJKR			

## Qualification Report

## Approve Date 19-May-2021

### Qualification Results Data Displayed as: Number of lots / Total sample size / Total failed

				Data Displayed	as. Number of lots	Total Sample Size	i otal lalleu			
Туре	Test Name / Condition	Duration	Qual Device: TPS65992DADRJKR	Qual Device: TPS65992DADRJKR	Qual Device: TPS65992SADRSMR	Qual Device: TPS65992SADRSMR	QBS Process Reference: TPS51486RJER	QBS Product Reference: TPS65992RSM	QBS Product Reference: TPS65992RSMR	QBS Package Reference: TPD5S330RJK
AC	Autoclave 121C	96 Hours	-	-	-	-	3/231/0	1/77/0	-	3/231/0
CDM	ESD - CDM	500 V	-	-	-	1/3/0	3/9/0	-	1/3/0	1/3/0
ED	Electrical Characterization	Per Datasheet Parameters	-	-	-	1/30/0	3/90/0	-	1/Pass	1/30/0
ELFR	Early Life Failure Rate, 125C	48 hours	-	-	-	-	3/2400/0	-	-	-
HAST	Biased HAST, 110C/85%RH	264 hours	-	-	-	-	2/231/0	1/77/0	-	3/231/0
HBM	ESD - HBM	1000 V	-	-	-	1/3/0	-	-	1/3/0	-
HBM	ESD - HBM	2000 V	-	-	-	-	3/9/0	-	-	-
HTOL	Life Test, 125C	1000 hours	-	-	-	1/77/0	3/231/0	2/154/0	1/77/0	3/231/0
HTSL	High Temp Storage Bake 170C	420 Hours	-	-	-	-	3/231/0	1/77/0	-	3/231/0
LU	Latch-up, 25C	(Per JESD78, Class I)	-	-	-	1/6/0	3/18/0	-	1/6/0	-
LU	Latch-up, 125C	(per JESD78)	-	-	-	1/6/0	3/18/0	-	-	-
MQ	Manufacturability (Assembly)	(per mfg. Site specification)	1/Pass	1/Pass	1/Pass	1/Pass	3/Pass	-	1/Pass	3/3/0
MQ	Manufacturability (Wafer Fab)	(Approved by Fab)	-	-	-	1/Pass	3/Pass	-	1/Pass	-
TC	Temperature Cycle, -65/150C	500 cycles	-	-	-	1/77/0	3/231/0	1/77/0	-	3/231/0

- QBS: Qual By Similarity
   Qual Device TPS65992DADRJKR is qualified at LEVEL2-260C
   Qual Device TPS65992DADRJKR contains multiple dies.

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV: 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
   The following are equivalent HTSL options based on an activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours
   The following are equivalent Temp Cycle options per JESD47: -55C/125C/700 Cycles and -65C/150C/500 Cycles
  Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

Green/Pb-free Status: Qualified Pb-Free (SMT) and Green

### Qualification Report

### Approve Date 24-August-2021

## Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Туре	Test Name / Condition	Duration	Qual Device: TPS65991AERSMR	Qual Device: TPS65992SAERSMR	Qual Device: TPS65992DAERJKR	QBS Product Reference: TP S65992 SADR SMR	QBS Process Reference: TPS51486RJER	QBS Product Reference: TPS65992RSM	QBS Product Reference: TPS65992RSMR	QBS Package Reference: TPD5 \$330RJK
AC	Autoclave 121C	96 Hours	-	-	-	-	3/231/0	1/77/0	-	3/231/0
CDM	ESD - CDM	500 V	-	-	-	1/3/0	3/9/0	-	1/3/0	1/3/0
ED	Electrical Characterization	Per Datasheet Parameters	-	-	-	1/30/0	3/90/0	-	1/Pass	1/30/0
ELFR	Early Life Failure Rate, 125C	48 hours	-	-	-	-	3/2400/0	-	-	-
HAST	Biased HAST, 110C/85%RH	264 hours	-	-	-	,	2/231/0	1/77/0	-	3/231/0
нвм	ESD - HBM	1000 V	-	-	-	1/3/0	-	-	1/3/0	-
нвм	ESD - HBM	2000 V	-	-	-	-	3/9/0	-	-	-
HTOL	Life Test, 125C	1000 hours	-	-	-	1/77/0	3/231/0	2/154/0	1/77/0	3/231/0
HTSL	High Temp Storage Bake 170C	420 Hours	-	-	-	-	3/231/0	1/77/0	-	3/231/0
LU	Latch-up, 25C	(Per JESD78, Class I)	-	-	-	1/8/0	3/18/0	-	1/6/0	-
LU	Latch-up, 125C	(per JESD78)	-	-	-	1/6/0	3/18/0	-	-	-
MQ	Manufacturability (Assembly)	(per mfg. Site specification)	1/Pass	1/Pass	1/Pass	1/Pass	3/Pass	-	1/Pass	3/3/0
MQ	Manufacturability (Wafer Fab)	(Approved by Fab)	-	-	-	1/Pass	3/Pass	•	1/Pass	•
TC	Temperature Cycle, -65/150C	500 cycles	-	-	-	1/77/0	3/231/0	1/77/0	-	3/231/0
YLD	Yield Evaluation	(per mfg. Site specification)	1/Pass	1/Pass	1/Pass	-	1	1	-	1

- QBS: Qual By Similarity
- Qual Device TPS65991AERSMR is qualified at LEVEL2-260C
- Qual Device TPS65992DAERJKR is qualified at LEVEL2-260C
- Qual Device TPS65992SAERSMR is qualified at LEVEL2-260C
- Device TPS65992DAERJKR contains multiple die
- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV: 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours - The following are equivalent HTSL options based on an activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours
- The following are equivalent T15E options based on an activation energy of 6.7eV. 130C/tk 110ths, and 170C/420
   The following are equivalent Temp Cycle options per JESD47: -55C/125C/700 Cycles and -65C/150C/500 Cycles

Ine following are equivalent Temp Cycle options per JESD47: -55C/125C/100 Cycles (Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

Green/Pb-free Status:

Qualified Pb-Free (SMT) and Green

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